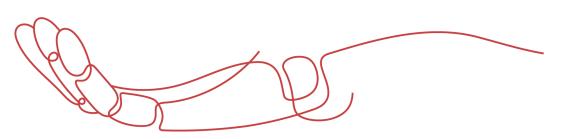




PRODUCT DATA SHEET



To learn more about JGSEMI, please visit our website at







Datasheet

es Samples

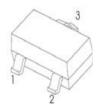
Please note: Please check the JINGAO Semiconductor website to verify the updated device numbers. The most current and up-to-date ordering information can be found at www.jg-semi.cn. Please email any questions regarding the system integration to JINGAO_questions@jgsemi.com.

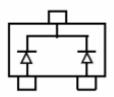
SCHOTTKY DIODES

SOT23-3L

FEATURES

• Extremely Fast Switching Speed





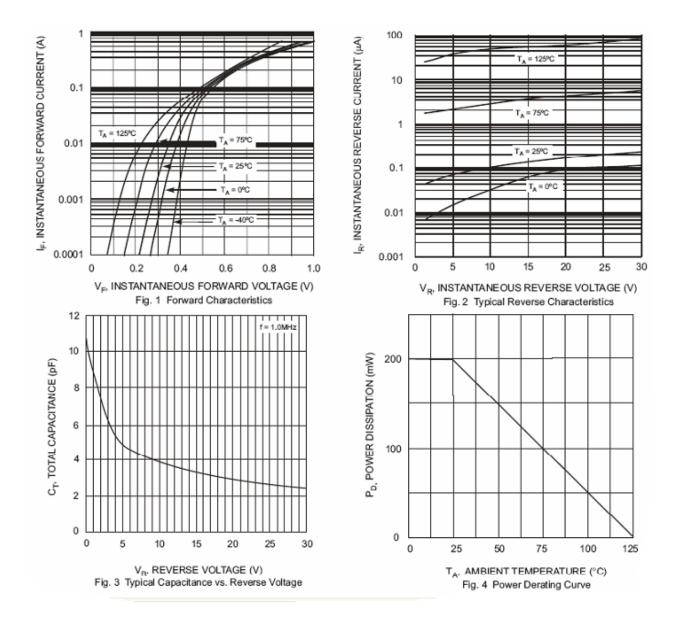
Maximum Ratings @T_A=25℃

Parameter	Symbol	Limits	Unit
Peak Repetitive Peak reverse voltage	V_{RRM}		
Working Peak Reverse Voltage	${\sf V}_{\sf RWM}$	30	V
DC BI ki V It Forward Continuous Current	I _{FM}	200	mA
Power Dissipation	P_{D}	200	mW
Storage temperature	T _{STG}	-55-150	°C

Electrical Characteristics $@T_A=25^{\circ}C$

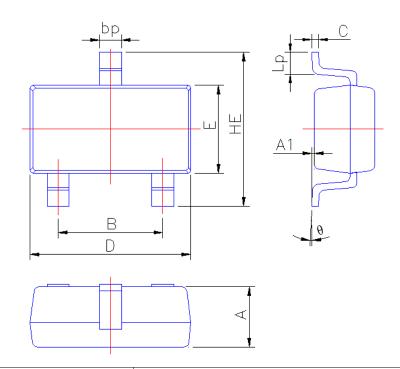
Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions
Reverse Breakdown Voltage	V _{(BR)R}	30			V	IR=100μA
Forward voltage	V_{F1}			0.24	V	I _F =0.1mA
	V _{F2}			0.32	V	I _F =1mA
	V _{F3}			0.40	V	I _F =10mA
	V _{F4}			0.50	V	I _F =30mA
	V_{F5}			1	V	I _F =100mA
Reverse current	I _R			2	μΑ	V _R =25V
Diode Capacitance	C _D			10	pF	V _R =1V,f=1MHz
Reverse Recovery Time	t _{rr}			5	nS	$I_F=I_R=10\text{mA}$ $Irr=0.1XI_R,R_L=100\Omega$







SOT-23-3L-Package Outline Dimensions



Symbol	Dimension in Millimeters					
Зупрог	Min	Max				
А	1.05	1.20				
A1	0.010	0.100				
В	1.80	2.00				
bp	0.35	0.50				
С	0.09	0.15				
D	2.80	3.00				
E	1.50	1.70				
HE	2.60	3.00				
Lp	0.25	0.55				
θ	2°	6°				



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